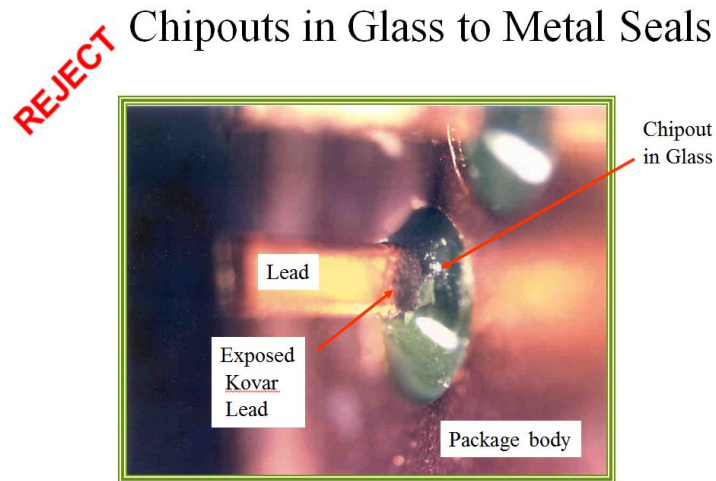


External Visual Inspection per Mil-Std-883 TM 2009 Course Outline (1/2 DAY)



Reject.. A significant chipout in the glass to metal seal which exposes the base Kovar metal on the lead.

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This course covers the visual inspection criteria for hermetic packaged microelectronic devices and similar devices and a review of typical plastic package defects in accordance with best commercial practices. Color photographs of actual production defects are reviewed and discussed in detail. The students are exposed to a variety of defects and the instructor explains why the defects are critical to the reliability of the end product.

- Understand what to look for as part of external visual inspection (TM 2009)
- Learn how to interpret and apply traditional Mil Spec visual inspection requirements
- Review products/defects “hands-on” in the Classroom as arranged

External Visual Inspection per TM 2009

Weld and Seal defects

Glass and ceramic feedthru defects e.g. meniscus cracking

Package marking and pin/lead defects

Inspection Criteria for Microelectronic Packages and Covers

Foreign Material Identification and Contamination Control

Review applicable criteria in **JESD 9B**

Plastic Package Defects

Summary and Review Q&A Session

Student Certification Test

Student Feedback and Course Critique